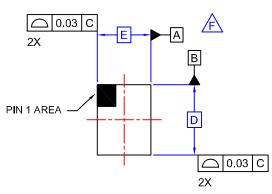
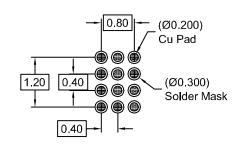
WLCSP12 1.615x1.415x0.586 CASE 567RY ISSUE O

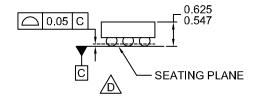
DATE 30 NOV 2016

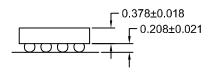




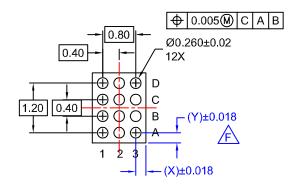
TOP VIEW

RECOMMENDED LAND PATTERN (NSMD PAD TYPE)





SIDE VIEWS



BOTTOM VIEW

NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
 - E. PACKAGE NOMINAL HEIGHT IS 586 MICRONS ±39 MICRONS (547-625 MICRONS).

FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

DESCRIPTION:			PAGE 1 OF 1
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